

**FOR IMMEDIATE RELEASE****Rohm and Haas Electronic Materials Exhibits at IPC Expo**

April 1-3, 2008, Mandalay Bay Resort & Convention Center, Las Vegas, Booth No. 1147

**Marlborough, MA, February 28, 2008** – Rohm and Haas Electronic Materials, exhibiting at this year's IPC show in Las Vegas, will present many new processes for the Printed Circuit market.

The company's ongoing focus on innovative electroless copper technology has led to Circuposit™ 3000-1 electroless copper, a universal process capable of vertical or horizontal application as well as low build or high build operation.

When chip packaging designs demand ultra fine conductors built by Semi-Additive technology, adhesion of the conductor to the substrate is an essential result of the metallization process. Circuposit 7800 adhesion promotion process delivers optimum surface roughness and subsequent metal adhesion on today's chip packaging substrate materials.

Rohm and Haas Electronic Materials' electroplating portfolio has also seen key developments in delivering solutions for high density boards. These include Copper Gleam™ XP6339 acid copper for pattern plate viafilling, Copper Gleam CuPulse™ acid copper for the best in pulse plating technology and Copper Gleam™ HT-55 acid copper, the latest in high performance DC electrolytic copper processes.

The printed circuit board industry continues to focus on final finish selection that cater to assembly and reliability requirements. The combination of Rohm and Haas's Duraposit™ SMT88 electroless nickel, Pallamerse™ SMT 2000 electroless palladium and Auroelectroless™ SMT-250 immersion gold provides a universal solution for multifunctional assembly requirements

In dry film technology, Rohm and Haas delivers advanced technology: for innerlayer, Laminar™ E-9000 and 9200 series; for outerlayer, Laminar E-7600; for laser direct imaging, Laminar UD-700; for general purpose, Laminar E-9200; and introducing ultra high resolution NIT Series dry films for HDI and build up applications. Rohm and Haas also offers Photoposit™ SN66 photoresist, the latest fast and durable liquid innerlayer resist. Enhancing the innerlayer product range is Circubond 2200 Plus, a new adhesion promotion process.

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**About Rohm and Haas Electronic Materials**

Rohm and Haas Electronic Materials develops and delivers innovative material solutions and processes to the electronic and optoelectronic industries. Focused on the circuit board, semiconductor manufacturing, advanced packaging, and flat panel display industries, its products and technologies are integral elements in electronic devices around the world.

**About Rohm and Haas's Circuit Board Technologies**

Focusing on metallization, imaging and optoelectronics applications, Rohm and Haas's Circuit Board Technologies business develops and delivers these industry-leading processes and products: electroless copper plating; electrolytic copper plating; liquid photoresists; dry film photoresists; stripper/etchant/developers; electroless nickel immersion gold; and adhesion promotion.

**About Rohm and Haas Company**

Leading the way since 1909, Rohm and Haas Company (NYSE:ROH) is a global pioneer in the creation and development of innovative technologies and solutions for the specialty materials industry. The company's technologies are found in a wide range of markets including: Building and Construction, Electronics, Food and Retail, Household and Personal Care, Industrial Process, Packaging, Paper, Transportation and Water. Our innovative technologies and solutions help to improve life everyday, around the world. Based in Philadelphia, PA, the company generated annual sales of approximately \$8.9 billion in 2007. Visit [www.rohmhaas.com](http://www.rohmhaas.com) for more information. Imagine the possibilities™.

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